

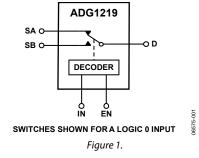
# Low Capacitance, Low Charge Injection, $\pm 15 \text{ V}/12 \text{ V} i \text{CMOS SPDT}$ in SOT-23

# ADG1219

#### FEATURES

<0.5 pC charge injection over full signal range 2.5 pF off capacitance Low leakage; 0.6 nA maximum @ 85°C 120 Ω on resistance Fully specified at +12 V, ±15 V No V<sub>L</sub> supply required 3 V logic-compatible inputs Rail-to-rail operation 8-lead SOT-23 package





### **APPLICATIONS**

Automatic test equipment Data acquisition systems Battery-powered systems Sample-and-hold systems Audio/video signal routing Communication systems

#### **GENERAL DESCRIPTION**

The ADG1219 is a monolithic *i*CMOS<sup>\*</sup> device containing an SPDT switch. An EN input is used to enable or disable the device. When disabled, all channels are switched off. When on, each channel conducts equally well in both directions and has an input signal range that extends to the supplies. Each switch exhibits break-before-make switching action.

The *i*CMOS (industrial CMOS) modular manufacturing process combines high voltage complementary metal-oxide semiconductor (CMOS) and bipolar technologies. It enables the development of a wide range of high performance analog ICs capable of 33 V operation in a footprint that no other generation of high voltage parts has been able to achieve. Unlike analog ICs using conventional CMOS processes, *i*CMOS components can tolerate high supply voltages while providing increased performance, dramatically lower power consumption, and reduced package size.

The ultralow capacitance and exceptionally low charge injection of these multiplexers make them ideal solutions for data acquisition and sample-and-hold applications, where low glitch and fast settling are required. Figure 2 shows that there is minimum charge injection over the entire signal range of the device. *i*CMOS construction also ensures ultralow power dissipation, making the parts ideally suited for portable and batterypowered instruments.

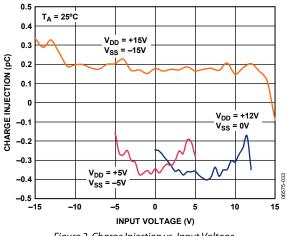


Figure 2. Charge Injection vs. Input Voltage

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### **REVISION HISTORY**

#### 3/09—Rev. 0 to Rev. A

Change to Power Requirements, $I_{\rm DD}$ Parameter, Ta	able 14
Change to Power Requirements, $I_{\rm DD}$ Parameter, $T_{\rm a}$	able 25
Updated Outline Dimensions	15

4/08—Revision 0: Initial Version

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### **SPECIFICATIONS**

### **DUAL SUPPLY**

 $V_{\text{DD}}$  = 15 V  $\pm$  10%,  $V_{\text{SS}}$  = –15 V  $\pm$  10%, GND = 0 V, unless otherwise noted.

#### Table 1.

_		B Versio			
Parameters	25°C	–40°C to +85°C	-40°C to +125°C	Unit	Test Conditions/Comments
ANALOG SWITCH					
Analog Signal Range			V <sub>DD</sub> to V <sub>SS</sub>	V	
On Resistance, R <sub>ON</sub>	120			Ω typ	$V_s = \pm 10 V$ , $I_s = -1 mA$ ; see Figure 23
	200	240	270	Ωmax	$V_{DD} = +13.5 \text{ V}, V_{SS} = -13.5 \text{ V}$
On Resistance Match Between Channels, ΔR <sub>ON</sub>	3.5			Ωtyp	$V_s = \pm 10 V$ , $I_s = -1 mA$
	6	10	12	Ωmax	
On Resistance Flatness, RFLAT(ON)	20			Ωtyp	$V_s = -5 V, 0 V, +5 V; I_s = -1 mA$
	64	76	84	Ωmax	
LEAKAGE CURRENTS					$V_{DD} = +16.5 V, V_{SS} = -16.5 V$
Source Off Leakage, I <sub>s</sub> (Off)	±0.004			nA typ	$V_{s} = \pm 10 V$ , $V_{s} = \pm 10 V$ ; see Figure 24
	±0.1	±0.6	±1	nA max	······································
Drain Off Leakage, I <sub>D</sub> (Off)	±0.009	_000		nA typ	$V_s = \pm 10 V$ , $V_s = \pm 10 V$ ; see Figure 24
	±0.1	±0.6	±1	nA max	vs=±10 v, vs=±10 v, see Figure 21
Channel On Leakage, I <sub>D</sub> , I <sub>s</sub> (On)	±0.1 ±0.02	_0.0		nA typ	$V_s = V_D = \pm 10 V$ ; see Figure 25
	±0.02 ±0.2	±0.6	±1	nA max	$v_{\rm S} = v_{\rm B} = \pm 10$ v, see Figure 25
DIGITAL INPUTS	±0.2	10.0	<u> </u>		
Input High Voltage, VINH			2.0	V min	
Input Low Voltage, VINH			0.8	V max	
Input Current, I <sub>INL</sub> or I <sub>INH</sub>	0.005		0.8	μA typ	$V_{\rm IN} = V_{\rm INI}$ or $V_{\rm INH}$
Input current, INL OF INH	0.005		±0.1		$\mathbf{v}_{\text{IN}} = \mathbf{v}_{\text{INL}} \mathbf{O} \mathbf{r} \mathbf{v}_{\text{INH}}$
Digital Input Capacitance, C <sub>IN</sub>	2		±0.1	μA max pF typ	
	2			рг тур	
Transition Time, transition	140			nc turn	$R_{L} = 300 \Omega, C_{L} = 35 pF$
Transition Time, transition	170	200	230	ns typ ns max	$V_s = 10 V$ ; see Figure 30
t <sub>on</sub> (EN)	85	200	230		$R_L = 300 \Omega$ , $C_L = 35 pF$
LON (EIN)	105	130	140	ns typ	$V_{s} = 10 V$ ; see Figure 30
+ (EN)	105	150	140	ns max	-
t <sub>off</sub> (EN)	105	150	170	ns typ	$R_L = 300 \Omega, C_L = 35 pF$
		150	170	ns max	$V_{s} = 10 V$ ; see Figure 30
Break-Before-Make Time Delay, $t_{\text{BBM}}$	40		10	ns typ	$R_L = 300 \Omega, C_L = 35 pF$
			10	ns min	$V_{s1} = V_{s2} = 10 V$ ; see Figure 31
Charge Injection	0.1			pC typ	$V_s = 0 V$ , $R_s = 0 \Omega$ , $C_L = 1 nF$ ; see Figure 32
Off Isolation	77			dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ; see Figure 26
Channel-to-Channel Crosstalk	80			dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ; see Figure 27
Total Harmonic Distortion + Noise	0.15			% typ	$R_L = 10 \text{ k}\Omega$ , 5 V rms, f = 20 Hz to 20 kHz
–3 dB Bandwidth	520			MHz typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ ; see Figure 28
Cs (Off)	2.5			pF typ	$f = 1 MHz; V_s = 0 V$
	3.3			pF max	$f = 1 MHz; V_s = 0 V$
C <sub>D</sub> (Off)	4.3			pF typ	$f = 1 MHz; V_s = 0 V$
	5.1			pF max	$f = 1 \text{ MHz}; V_s = 0 \text{ V}$
C <sub>D</sub> , C <sub>s</sub> (On)	7.5			pF typ	$f = 1 \text{ MHz}; V_s = 0 \text{ V}$
, (= ,	10			pF max	$f = 1 \text{ MHz}; V_s = 0 \text{ V}$

		B Versio	on <sup>1</sup>		
Parameters	25°C	–40°C to +85°C	–40°C to +125°C	Unit	<b>Test Conditions/Comments</b>
POWER REQUIREMENTS					$V_{DD} = +16.5 \text{ V}, V_{SS} = -16.5 \text{ V}$
I <sub>DD</sub>	0.001			μA typ	Digital inputs = $0 V \text{ or } V_{DD}$
			1.0	μA max	
I <sub>DD</sub>	140			μA typ	Digital inputs = 5 V
			190	μA max	
I <sub>SS</sub>	0.001			μA typ	Digital inputs = 0 V, 5 V or $V_{DD}$
			1.0	μA max	
V <sub>DD</sub> /V <sub>SS</sub>			±5/±16.5	V	$ V_{DD}  =  V_{SS} $
				min/max	

 $^1$  Temperature range for B version is  $-40^\circ$  C to  $+125^\circ$  C.  $^2$  Guaranteed by design; not subject to production test.

### SINGLE SUPPLY

 $V_{DD}$  = 12 V ± 10%,  $V_{SS}$  = 0 V, GND = 0 V, unless otherwise noted.

#### Table 2.

	B Version <sup>1</sup>						
Parameters	25°C	-40°C to +85°C	-40°C to +125°C	Unit	<b>Test Conditions/Comments</b>		
ANALOG SWITCH							
Analog Signal Range			$0 V to V_{\text{DD}}$	V			
On Resistance, Ron	300			Ωtyp	$V_s = 0 V$ to 10 V, $I_s = -1 mA$ ; see Figure 23		
	475	567	625	Ωmax	$V_{DD} = 10.8 \text{ V}, V_{SS} = 0 \text{ V}$		
On Resistance Match Between Channels, ΔR <sub>oN</sub>	4.5			Ωtyp	$V_{s}=0\ V\ to\ 10\ V,\ I_{s}=-1\ mA$		
	16	26	27	Ωmax			
On Resistance Flatness, R <sub>FLAT(ON)</sub>	60			Ωtyp	$V_s = 3 V, 6 V, 9 V, I_s = -1 mA$		
LEAKAGE CURRENTS					$V_{DD} = 13.2 V$		
Source Off Leakage, Is (Off)	±0.006			nA typ	$V_{\text{S}}$ = 1 V/10 V, $V_{\text{D}}$ = 10 V/1 V; see Figure 24		
	±0.1	±0.6	±1	nA max			
Drain Off Leakage, I <sub>D</sub> (Off)	±0.006			nA typ	$V_s = 1 \text{ V}/10 \text{ V}$ , $V_D = 10 \text{ V}/1 \text{ V}$ ; see Figure 24		
	±0.1	±0.6	±1	nA max			
Channel On Leakage, I <sub>D</sub> , I <sub>S</sub> (On)	±0.02			nA typ	$V_s = V_D = 1 V \text{ or } 10 V$ ; see Figure 25		
	±0.2	±0.6	±1	nA max			
DIGITAL INPUTS							
Input High Voltage, V <sub>INH</sub>			2.0	V min			
Input Low Voltage, V <sub>INL</sub>			0.8	V max			
Input Current, I <sub>INL</sub> or I <sub>INH</sub>	0.001			μA typ	$V_{\text{IN}} = V_{\text{INL}} \text{ or } V_{\text{INH}}$		
			±0.1	μA max			
Digital Input Capacitance, C <sub>IN</sub>	3			pF typ			
DYNAMIC CHARACTERISTICS <sup>2</sup>							
Transition Time, transition	195			ns typ	$R_L = 300 \ \Omega, C_L = 35 \ pF$		
	250	300	340	ns max	V <sub>s</sub> = 8 V; see Figure 30		
t <sub>on</sub> (EN)	120			ns typ	$R_L = 300 \ \Omega, C_L = 35 \ pF$		
	150	190	210	ns max	V <sub>s</sub> = 8 V; see Figure 30		
t <sub>OFF</sub> (EN)	145			ns typ	$R_L = 300 \ \Omega, C_L = 35 \ pF$		
	185	220	255	ns max	V <sub>s</sub> = 8 V; see Figure 30		
Break-Before-Make Time Delay, t <sub>BBM</sub>	70			ns typ	$R_L = 300 \Omega, C_L = 35 pF$		
			10	ns min	$V_{s1} = V_{s2} = 8 V$ ; see Figure 31		
Charge Injection	-0.8			pC typ	$V_s = 6 V$ , $R_s = 0 \Omega$ , $C_L = 1 nF$ ; see Figure 32		
Off Isolation	80			dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ; see Figure 26		
Channel-to-Channel Crosstalk	80			dB typ	$R_L = 50 \Omega$ , $C_L = 5 pF$ , $f = 1 MHz$ ; see Figure 27		
–3 dB Bandwidth	400			MHz typ	$R_{L} = 50 \Omega$ , $C_{L} = 5 pF$ ; see Figure 28		

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		B Versio	n <sup>1</sup>		
Parameters	25°C	–40°C to +85°C	–40°C to +125°C	Unit	Test Conditions/Comments
C <sub>s</sub> (Off)	2.9			pF typ	$f = 1 MHz; V_s = 6 V$
	3.7			pF max	$f = 1 MHz; V_s = 6 V$
C <sub>D</sub> (Off)	5			pF typ	$f = 1 MHz; V_s = 6 V$
	5.8			pF max	$f = 1 MHz; V_s = 6 V$
C <sub>D</sub> , C <sub>s</sub> (On)	8.5			pF typ	$f = 1 MHz; V_s = 6 V$
	11			pF max	$f = 1 MHz; V_s = 6 V$
POWER REQUIREMENTS					V <sub>DD</sub> = 13.2 V
l <sub>DD</sub>	0.001			μA typ	Digital inputs = $0 V \text{ or } V_{DD}$
			1.0	μA max	
I <sub>DD</sub>	140			μA typ	Digital inputs = 5 V
			190	µA max	
V <sub>DD</sub>			5/16.5	V min/max	$V_{ss} = 0 V, GND = 0 V$

 $^1$  Temperature range for B version is  $-40^\circ C$  to  $+125^\circ C.$   $^2$  Guaranteed by design; not subject to production test.

### **ABSOLUTE MAXIMUM RATINGS**

 $T_A = 25^{\circ}C$ , unless otherwise noted.

#### Table 3.

Parameter	Rating
V <sub>DD</sub> to V <sub>SS</sub>	35 V
V <sub>DD</sub> to GND	–0.3 V to +25 V
Vss to GND	+0.3 V to -25 V
Analog Inputs <sup>1</sup>	V <sub>ss</sub> – 0.3 V to V <sub>DD</sub> + 0.3 V or 30 mA, whichever occurs first
Digital Inputs <sup>1</sup>	GND – 0.3 V to V <sub>DD</sub> + 0.3 V or 30 mA, whichever occurs first
Peak Current, S or D	100 mA (pulsed at 1 ms, 10% duty cycle maximum)
Continuous Current per Channel, S or D	30 mA
Operating Temperature Range	
Industrial (B Version)	-40°C to +125°C
Storage Temperature Range	–65°C to +150°C
Junction Temperature	150°C
8-Lead SOT-23, θ <sub>JA</sub> Thermal Impedance	211.5°C/W
Reflow Soldering Peak Temperature, Pb Free	260°C

<sup>1</sup> Overvoltages at IN, S, or D are clamped by internal diodes. Current should be limited to the maximum ratings given.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ESD CAUTION**



**ESD (electrostatic discharge) sensitive device.** Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

## **PIN CONFIGURATION AND FUNCTION DESCRIPTIONS**



Figure 3. SOT-23 Pin Configuration

#### **Table 4. Pin Function Descriptions**

Pin No.	Mnemonic	Description
1	EN	Active High Digital Input. When this pin is low, the device is disabled and all switches are turned off. When this pin is high, the IN logic input determines which switch is turned on.
2	V <sub>DD</sub>	Most Positive Power Supply Potential.
3	GND	Ground (0 V) Reference.
4	V <sub>ss</sub>	Most Negative Power Supply Potential.
5	SB	Source Terminal. Can be an input or output.
6	D	Drain Terminal. Can be an input or output.
7	SA	Source Terminal. Can be an input or output.
8	IN	Logic Control Input.

#### Table 5. Truth Table

EN	IN	Switch A	Switch B
0	Х	Off	Off
1	0	On	Off
1	1	Off	On

### **TYPICAL PERFORMANCE CHARACTERISTICS**

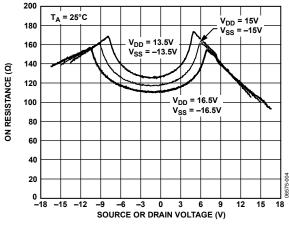
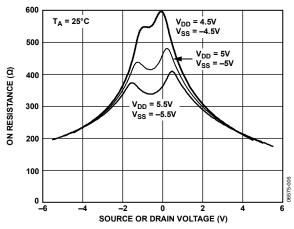


Figure 4. On Resistance as a Function of  $V_D$  ( $V_S$ ) for Dual Supply





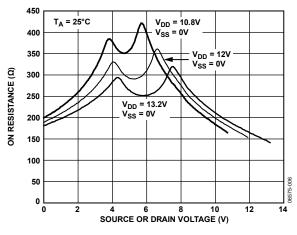


Figure 6. On Resistance as a Function of  $V_D$  ( $V_S$ ) for Single Supply

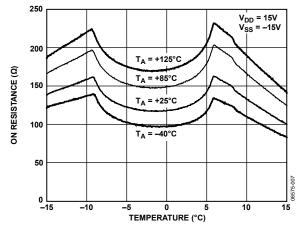


Figure 7. On Resistance as a Function of  $V_D$  ( $V_S$ ) for Different Temperatures, Dual Supply

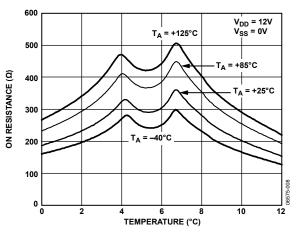


Figure 8. On Resistance as a Function of V<sub>D</sub> (V<sub>s</sub>) for Different Temperatures, Single Supply

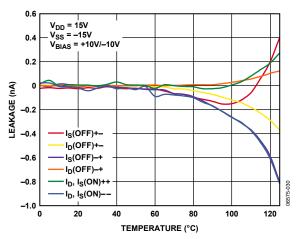


Figure 9. Leakage Currents as a Function of Temperature, 15 V Dual Supply

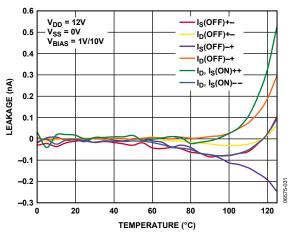


Figure 10. Leakage Currents as a Function of Temperature, 12 V Single Supply

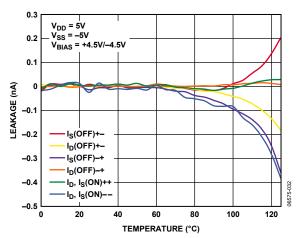
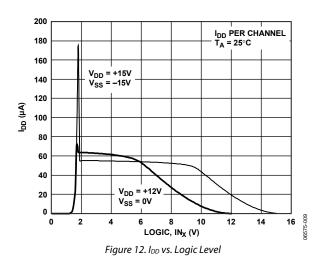
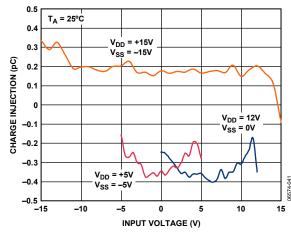
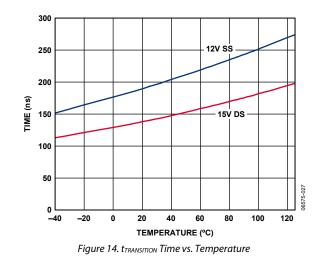


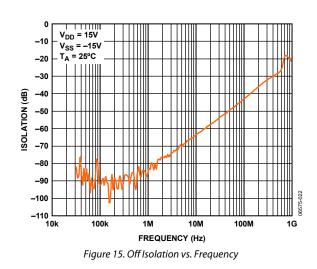
Figure 11. Leakage Currents as a Function of Temperature, 5 V Dual Supply

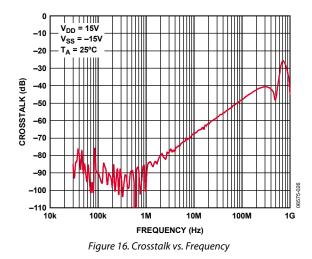












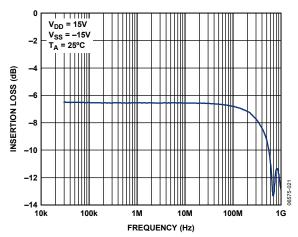


Figure 17. On Response vs. Frequency

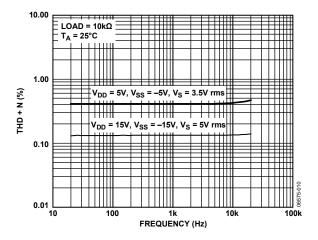


Figure 18. THD + N vs. Frequency

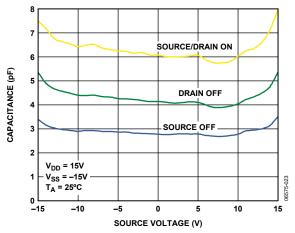


Figure 19. Capacitance vs. Source Voltage for Dual Supply

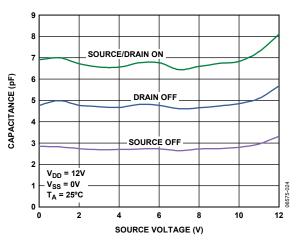


Figure 20. Capacitance vs. Source Voltage for Single Supply

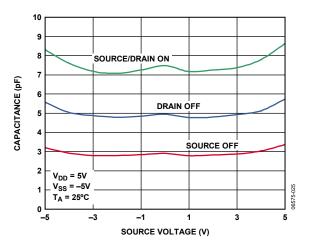
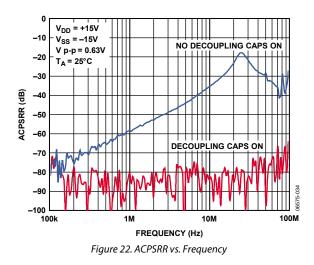


Figure 21. Capacitance vs. Source Voltage for Dual Supply



### **TEST CIRCUITS**

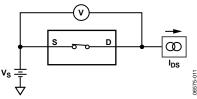
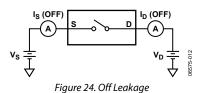


Figure 23. On Resistance



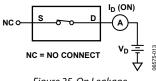


Figure 25. On Leakage

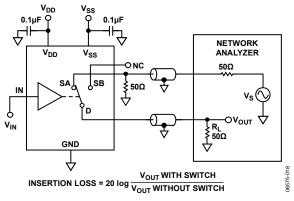


Figure 27. Channel-to-Channel Crosstalk

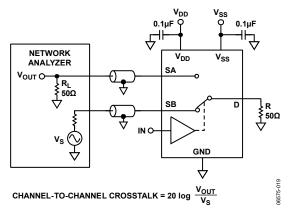
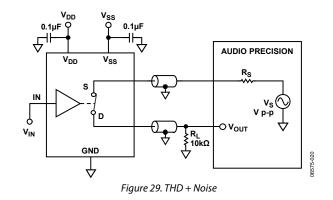
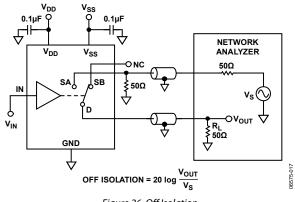
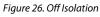
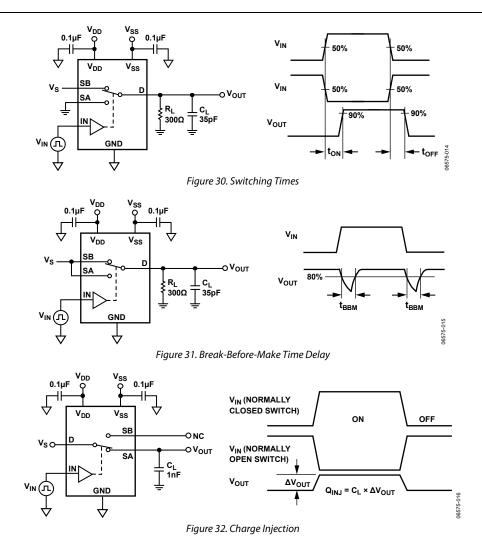


Figure 28. Bandwidth









### TERMINOLOGY

Idd

The positive supply current.

Iss

The negative supply current.

V<sub>D</sub> (V<sub>s</sub>) The analog voltage on Terminal D and Terminal S.

### Ron

The ohmic resistance between Terminal D and Terminal S.

### R<sub>FLAT(ON)</sub>

Flatness is defined as the difference between the maximum and minimum value of on resistance as measured over the specified analog signal range.

### Is (Off)

The source leakage current with the switch off.

 $\mathbf{I}_{\mathrm{D}}$  (Off) The drain leakage current with the switch off.

 $I_{\rm D},\,I_{\rm S}\left(On\right)$  The channel leakage current with the switch on.

V<sub>INL</sub> The maximum input voltage for Logic 0.

 $V_{\mbox{\scriptsize INH}}$  The minimum input voltage for Logic 1.

I<sub>INL</sub> (I<sub>INH</sub>) The input current of the digital input.

### Cs (Off)

The off switch source capacitance, measured with reference to ground.

### C<sub>D</sub> (Off)

The off switch drain capacitance, measured with reference to ground.

### $C_D$ , $C_s$ (On)

The on switch capacitance, measured with reference to ground.

### CIN

The digital input capacitance.

### ton (EN)

Delay time between the 50% and 90% points of the digital input and switch on condition.

### toff (EN)

Delay time between the 50% and 90% points of the digital input and switch off condition.

#### **t**TRANSITION

Delay time between the 50% and 90% points of the digital inputs and the switch on condition when switching from one address state to another.

Тввм

Off time measured between the 80% point of both switches when switching from one address state to another.

### **Charge Injection**

A measure of the glitch impulse transferred from the digital input to the analog output during switching.

### **Off Isolation**

A measure of unwanted signal coupling through an off switch.

### Crosstalk

A measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance.

### Bandwidth

The frequency at which the output is attenuated by 3 dB.

**On Response** The frequency response of the on switch.

**Insertion Loss** The loss due to the on resistance of the switch.

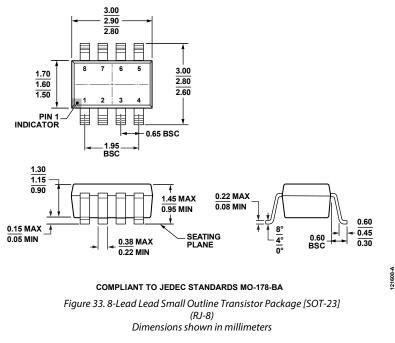
**Total Harmonic Distortion (THD + N)** 

The ratio of the harmonic amplitude plus noise of the signal to the fundamental.

### AC Power Supply Rejection Ratio (ACPSRR)

Measures the ability of a part to avoid coupling noise and spurious signals that appear on the supply voltage pin to the output of the switch. The dc voltage on the device is modulated by a sine wave of 0.62 V p-p. The ratio of the amplitude of signal on the output to the amplitude of the modulation is the ACPSRR.

### **OUTLINE DIMENSIONS**



### **ORDERING GUIDE**

Model	Temperature Range	Package Description	Package Option	Branding
ADG1219BRJZ-R21	-40°C to +125°C	8-Lead Lead Small Outline Transistor Package [SOT-23]	RJ-8	S24
ADG1219BRJZ-REEL71	-40°C to +125°C	8-Lead Lead Small Outline Transistor Package [SOT-23]	RJ-8	S24

 $^{1}$  Z = RoHS Compliant Part.

### NOTES

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